



EDER Engineering at Wire Dusseldorf 2020

*Offering innovative and high value added concepts with over 70 years of expertise in the field of reconditioning die working equipments, EDER-Austria is sustaining and developing its distinctive advanced position across the globe and is presenting its various technologically leading machines at **Hall 10/C42- 01** at Wire Duesseldorf 2020.*



Figure 1

At **WIRE 2020**, now taking place between December 7 to 11 in Duesseldorf and at their huge **stand No.10/C42-01**, **EDER** will offer a variety of latest technological developments in drawing die-tool working machines, allowing the users to **benefit by**:

- longer life of the dies and higher tonnage drawn;
- accurate reconditioning of the die; durability with minimal maintenance costs;
- lower operational cost; reduction of manpower (due to high degree of automation built-in); easy operation; and last, not least....
- 70 years of experience and proven after-sale support of EDER-Austria.

The following exhibits/developments will be displayed in Duesseldorf:

- **Leading die-tool processing machines** for the repair and/or production of ultrahard tungsten carbide-, diamond-, PCD precision die-tools. (standard-, semi- automatic- and automatic conceptions).
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- **Die workshop ancillary equipment** (cleaning/measuring devices, microscopes etc.)
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- **Technical assistance programs** (installation, training, die-reconditioning etc.)
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- **Die tool working materials** (eg. Diamond powders, pastes, suspensions, grinding-, sizing- and measuring pins etc.)



Figure 2

Some examples of unmatched EDER machines at WIRE 2020 that will be presented live by EDER's staff and/or on a video wall:

“ETC-1/HF”: Efficient tungsten carbide die grinding and polishing equipment with a very large work-range of between 0.70 up to 20 mm dia. *See Figure 1*

“USP-TWIN”: Particularly for refurbishing of the continuously growing quantity of PCD dies in use at multi-wire drawing machines, a unique Ultrasonic machine, model “USP-TWIN”, with two workstations has been developed, which can efficiently work all die-sizes in a large range between 0.05 up to 8.0 mm dia. It can be operated by one only person, same time doubling output.

See Figure 2



Fig. 3: showing EDER equipment in successful die workshop operations.

“ETC-2 LS”: For sizing and polishing **tungsten carbide dies** in the larger bore size range, of between 1.0 up to even 40 mm dia.

A new larger **“ETC-3 EL”** unit works round **Tc dies** with bigger bore-sizes up to 70 mm dia. Additionally, some special die-workshop ancillary devices and other machines also will be demonstrated at the Eder stand.

Other equipment for processing of **diamond/PCD dies** shown will be the Ultrasonic model **USP-115** and the High-Speed Wire-Type **HGM-21** sizing/calibrating machine

*We would like to welcome YOU at our **booth 10/C42-01** to discuss industry’s new trends and concepts, particularly showing ultimate solutions for the efficient reconditioning of dies and would be pleased to visualise the many benefits, outstanding potentials and capabilities of EDER machines.*

At the EDER-Stand 10C/42-01, the following staff and experts will be at your disposal:

Dr. Kurt EDER, Mr. Willi Eberhardt, Mr. Bernhard EDER, Mrs. Marina EDER and international EDER-representatives.

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Only good dies draw good wire !